

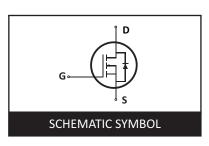
## **N-CHANNEL POWER MOSFET**

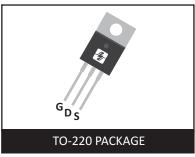
## **DESCRIPTION**

This MOSFET is produced with advanced VDMOS technology of SEMIWILL. This technology enable power MOSFET to have better characteristics, such as fast switching time, low on resistance, low gate charge and especially excellent avalanche characteristics. This power MOSFET is usually used at high efficient DC to DC converter block and SMPS. It's typical application is TV and monitor.

## **FEATURES**

- High ruggedness
- RDS(ON)(Max. 0.008Ω)@VGS=10V
- Gate Charge (Typ.126nC)
- Improved dv/dt Capability
- 100% Avalanche Tested





#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter		Value	Unit	
V <sub>DSS</sub>	Drain to Source Voltage		75	V	
	Continuous Drain Current (@T <sub>c</sub> =25 °C)		75	А	
I <sub>D</sub>	Continuous Drain Current (@T <sub>C</sub> =100 °C)		70	А	
I <sub>DM</sub>	Drain current pulsed	(note 1)	280	А	
V <sub>GS</sub>	Gate to Source Voltage		±20	V	
E <sub>AS</sub>	Single pulsed Avalanche Energy	(note 2)	1674	mJ	
E <sub>AR</sub>	Repetitive Avalanche Energy	(note 1)	45	mJ	
dv/dt	Peak diode Recovery dv/dt	(note 3)	7	V/ns	
_	Total power dissipation (@T <sub>C</sub> =25 °C)		312	W	
$P_{D}$	Derating Factor above 25°C		2.5	W/°C	
T <sub>STG</sub> , T <sub>J</sub>	Operating Junction Temperature & Storage Temperature		-55 ~ + 150	°C	
T <sub>L</sub>	Maximum Lead Temperature for soldering purpose, 1/8 from Case for 5 seconds.		300	°C	

## THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
R <sub>thjc</sub>	Thermal resistance, Junction to case 0.4		°C/W
R <sub>thja</sub>	Thermal resistance, Junction to ambient	60	5, **



# **ELECTRICAL CHARACTERISTIC** ( $T_C = 25^{\circ}C$ unless otherwise specified )

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Off charact	eristics					
BV <sub>DSS</sub>	Drain to source breakdown voltage	VGS=0V,ID=250uA	75	-	-	V
I <sub>DSS</sub>	Drain to source leakage current	V <sub>DS</sub> =75V,V <sub>GS</sub> =0V	-	-	1	uA
		V <sub>DS</sub> =75V,Tc=125°C	-	-	20	uA
I <sub>GSS</sub>	Gate to source leakage current, forward	V <sub>DS</sub> =20V,V <sub>GS</sub> =0V	-	-	100	nA
	Gate to source leakage current, reverse	VDS=-20V,VGS=0V	-	-	-100	nA
On characte	eristics					
V <sub>GS(TH)</sub>	Gate threshold voltage	VDS=VGS,ID=250uA	2.0	-	4.0	V
R <sub>DS(ON)</sub>	Drain to source on state resistance	Vgs=10V,ID=40A			0.008	Ω
Dynamic ch	aracteristics					
C <sub>iss</sub>	Input capacitance	Vgs=0V,Vbs=25V,f=1MHz	-	960	1260	pF
C <sub>oss</sub>	Output capacitance		-	110	135	
C <sub>rss</sub>	Reverse transfer capacitance		-	15	18	
$t_{d(on)}$	Turn on delay time	VDS=37.5V,ID=75A,RG=25ohm (note 4,5)	-	37	80	ns
tr	Rising time		-	67	100	
t <sub>d(off)</sub>	Turn off delay time		-	72	150	
t <sub>f</sub>	Fall time		-	30	80	
Q <sub>g</sub>	Total gate charge	Vps=60V,Vgs=10V,Ip=75A (note 4,5)	-	126	180	
$Q_{gs}$	Gate -source charge		-	46	-	nC
$Q_{gd}$	Gate -drain charge		-	47	-	

## **SOURCE TO DRAIN DIODE RATINGS CHARACTERISTICS**

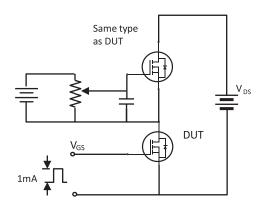
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Is	Continuous source current	Integral reverse p-n Junction diode in the MOSFET	-	-	75	А
I <sub>SM</sub>	Pulsed source current		-	-	300	А
V <sub>SD</sub>	Diode forward voltage drop.	Is=75A, VGS=0V	-	-	1.2	V
Trr	Reverse recovery time	Is=75A, Vgs=0V	-	36.5	-	ns
Q <sub>rr</sub>	Breakdown voltage temperature	dlF/dt=100A/us	-	52	-	nC

#### Notes

- 1. Repeatitive rating : pulse width limited by junction temperature.
- 2. L = 0.36mH, IAS= 75A, VDD= 50V, RG=25 $\Omega$ , Starting TJ= 25 $^{\circ}$  C
- 3. Isp $\leq$  75A, di/dt = 100A/us, VDD $\leq$  BVDss, Staring TJ=25°C
- 4. Pulse Test : Pulse Width ≤ 300us, duty cycle ≤ 2%
- $5. \ Essentially independent of operating temperature.\\$



Fig. 1. Gate charge test circuit & waveform



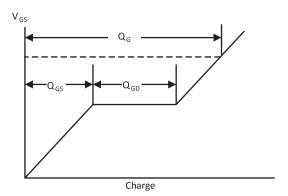
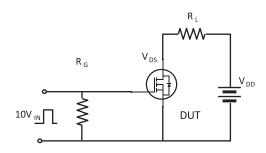


Fig. 2. Switching time test circuit & waveform



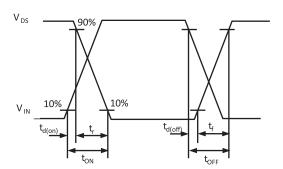
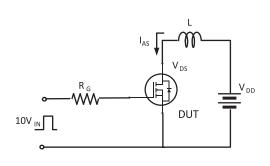
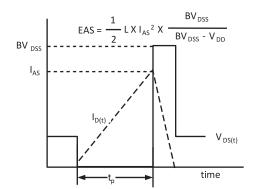


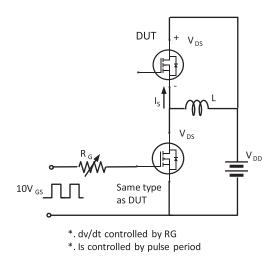
Fig. 3. Unclamped Inductive switching test circuit & waveform

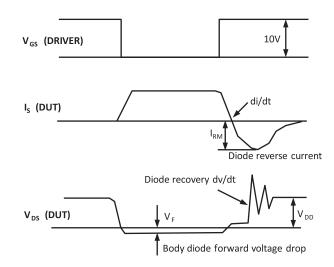






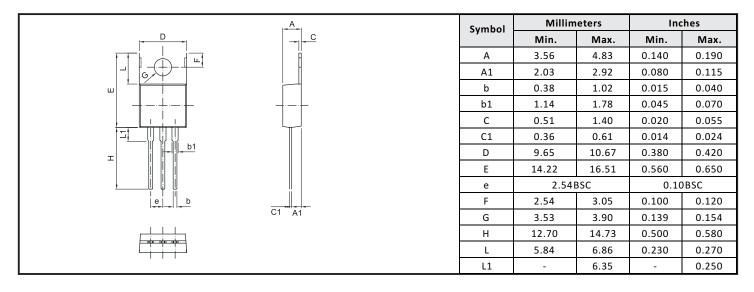
## Fig. 4. Peak diode recovery dv/dt test circuit & waveform





## **PACKAGE DIMENSIONS**

#### **TO-220AB**





## **CONTACT US**

#### He adquarters

A Building Caohejing I&E Park Pujiang Minhang Shanghai China

#### Web

http://www.semiwill.com

#### By Telephone

General: 86-21-34637654 Sales: 86-21-34637458 Customer Service: 86-21-34637172

#### By Email

Sales: sales@semiwill.com Customer Service: cs@semiwill.com Technical Support: fae@semiwill.com

#### By Fax

General: 86-21-34637173 Sales: 86-21-39650654

 ${\tt COPYRIGHT @SEMIWILL\ 2009-This\ literature\ is\ subject\ to\ all\ applicable\ copyright\ laws\ and\ is\ not\ for\ resale\ in\ any\ manner.}$ 

SPECIFICATIONS: SEMIWILL reserves the right to change the electrical and or mechanical characteristics described herein without notice.

DESIGN CHANGES: SEMIWILL reserves the right to discontinue product lines without notice and that the final judgement concerning selection and specifications is the buyer's and that in furnishing engineering and technical assistance. SEMIWILL assumes no responsibility with respect to the selection or specifications of such products. SEMIWILL makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SEMIWILL assume any liability arising out of the application or use of any product or circuit and specifically disclaims any and all liability without limitation special, consequential or incidental damages.

LIFE SUPPORT POLICY: SEMIWILL products are not authorized for use in life support systems without written consent from the factory.